

CHIP FABRICATION METHOD

ABSTRACT

Disclosed is a chip fabrication method for fabricating chips by dividing a wafer having a film formed on a reverse surface thereof, along planned division lines into individual chips, the method including a laser beam irradiation step of irradiating the wafer with a laser beam along the planned division lines set on the wafer, to form ablation marks in the film formed on the reverse surface and to form modified regions inside the wafer, and a division step of applying an external force to the wafer after the laser beam irradiation step has been carried out, to divide the wafer along the ablation marks formed in the laser beam irradiation step.

[FIG. 3]